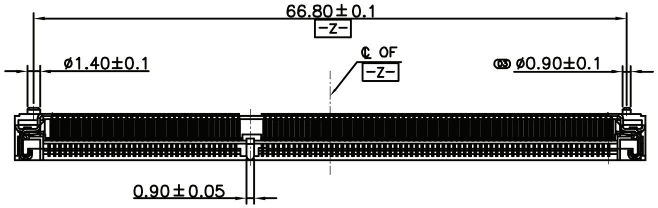
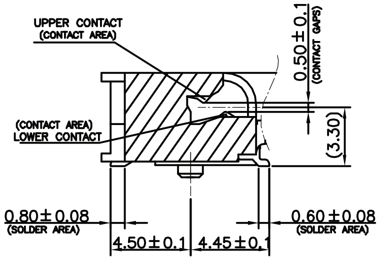
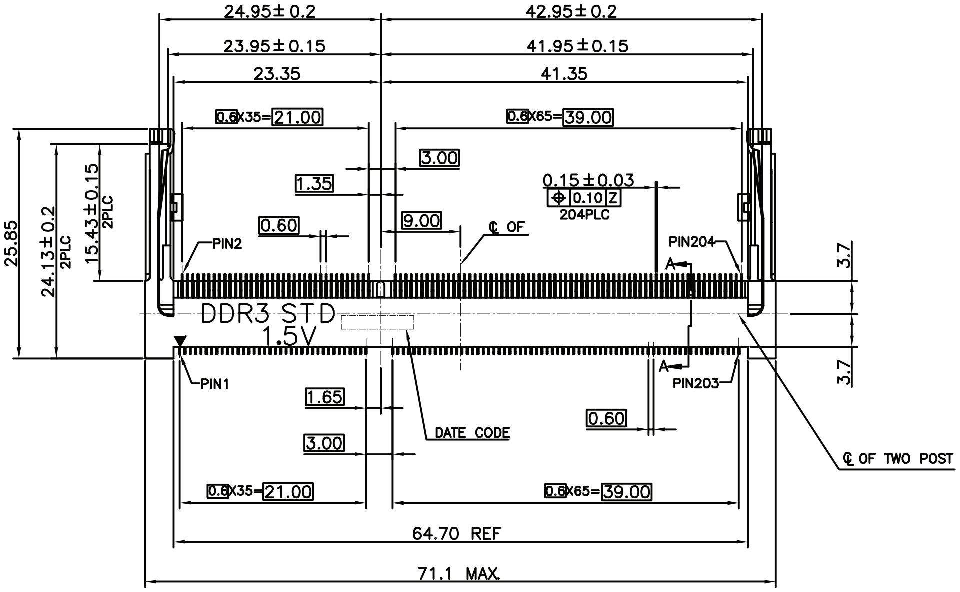
NOTES:
1. Recommended Reflow Temperature 260˚C (5 Sec.)
2. Voltage Rating: 25 VAC
3. Current Rating: 0.5 A
4. Temperature Rating: -55 C to 85 C

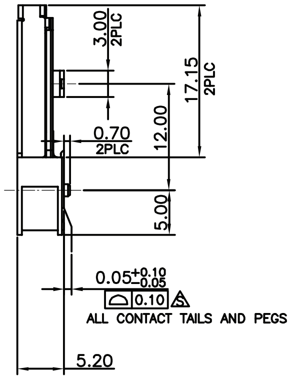




SCALE 2:1

SECTION A–A





HOW TO ORDER:

B 0 3 0 - 2 0 4 3 - A 0 X X - Z

NUMBER OF CONTACTS:
204

KEY TYPE / VOLTAGE OPTION :
3 - 1.5V TYPE

DIM.A OPTION
A - 5.2mm

ORIENTATION:
0 - Standard

PLATING OPTIONS:
2 - Au FLASH
6 - 15u" Au

PACKAGING:
0 - Tray
1 - Tape & Reel (Normal)
2 - Tape & Reel (Reverse)

RoHS COMPLIANT

MATERIAL:
CONTACT PLATING: Specified Au Thickness in Contact Area
Au Flash on Solder Tails; 50u" Nickel Sub Plate
Nickel Sub Plate (80"m min)
HOUSING: High Temp Thermo Plastic UL94V-0, Black
METAL LATCH: Stainless Steel
FLOATING LATCH: Stainless Steel
FIXED LATCH: Stainless Steel
CONTACT: Copper Alloy

Rev	Description	Drawn	Checked	Approved	Date
0	Issued	B.S.	S.M.	S.M.	09/17/09
A	Revised Insulator and Soldering Peg	B.S.	S.M.	S.M.	07/14/10

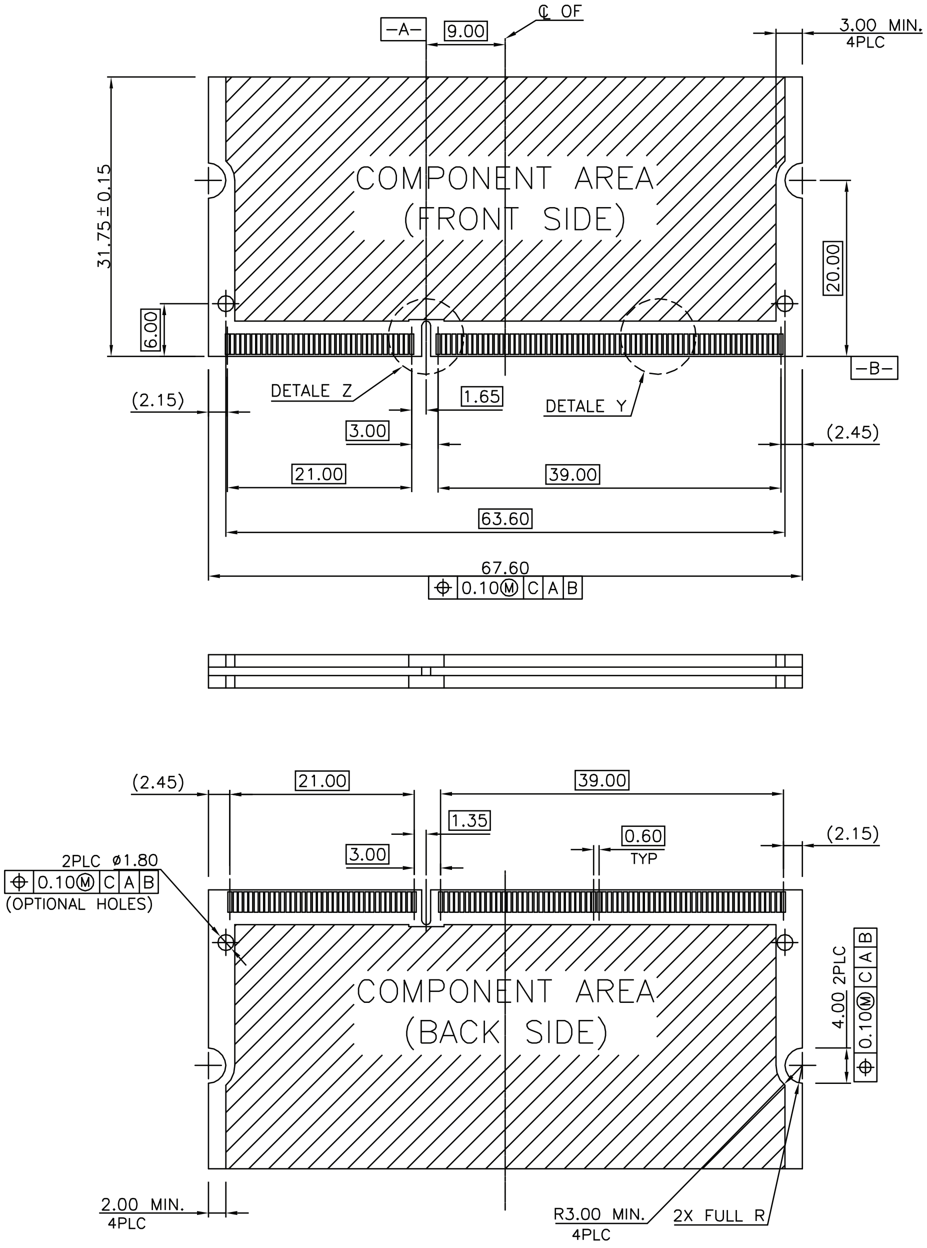
SMP TECHNOLOGY, INC.

DDR SO DIMM Socket, 204 Position, 1.5 Volt

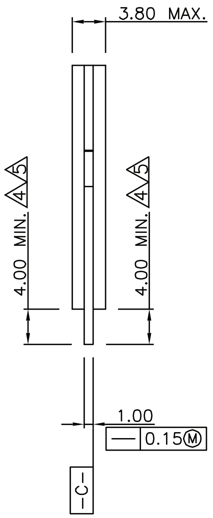
Standard Orientation, Right Angle, 5.2mm Height; Type 2

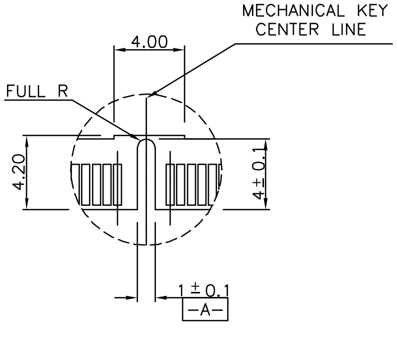
TOL. DEC. .X +/- 0.40 .XX +/- 0.25 .XXX +/- 0.15 .XXXX +/- 0.05 ANGLE +/- 3° UNIT: mm

P/N: B030-2043-A0XX-Z

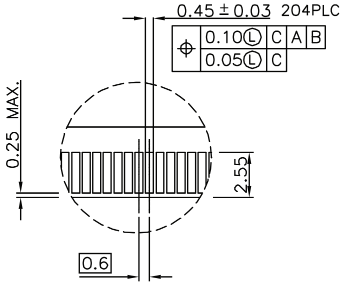


RECOMMENDED MATING P.C.B CONFIGURATION





DETAIL Z



DETAIL Y

NOTE:
1. TOLERANCES ON ALL DIMENSIONS ±0.15 UNLESS OTHERWISE SPECIFIED.
2. P.C.BOARD THICKNESS APPLIES ACROSS TABS
AND INCLUDES PLATING AND/OR MENTAIZATION.
3. FINISH OF PAD:GOLD PLATING 0.00076MIN OVER ON PLATING 0.002MIN.
⚠4 DIMENSIONS APPLICABLE WHEN COMPONENTS MOUNTED ON BOTH SIDE.
PCB THICKNESS NOT TO BE EXCEEDED OUTSIDE OF COMPONENT AREA.
⚠5 BORDER OF COMPONENT AREA.

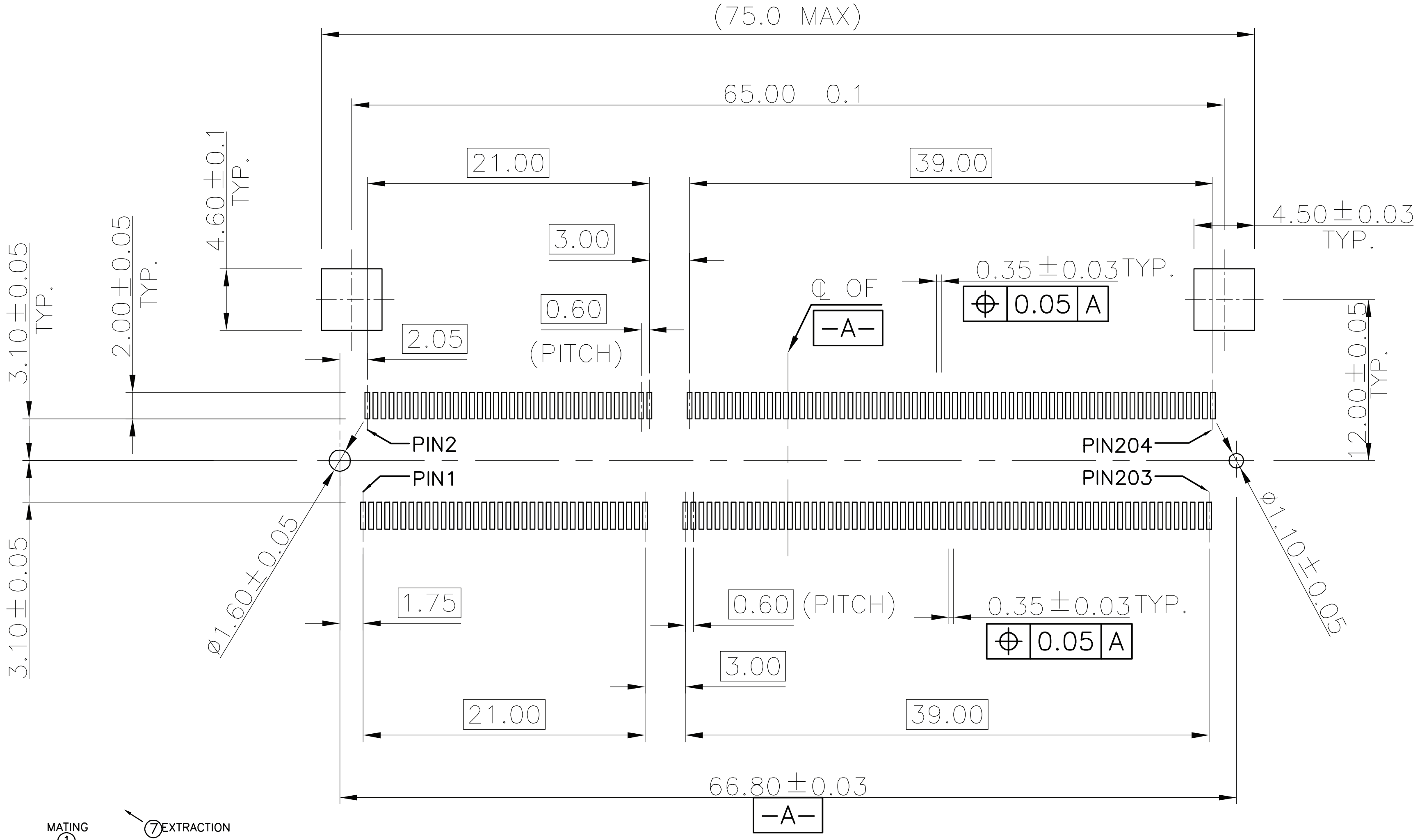
SMP TECHNOLOGY, INC.

DDR SO DIMM Socket, 204 Position, 1.5 Volt

Standard Orientation, Right Angle, 5.2mm Height; Type 2

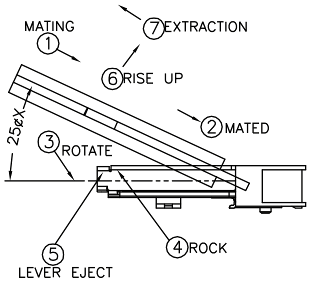
P/N: B030-2043-A0XX-Z

TOL. DEC. .X +/- 0.40 .XX +/- 0.25 .XXX +/- 0.15 .XXXX +/- 0.05 ANGLE +/- 3° UNIT: mm



RECOMMENDED PCB LAYOUT

THICKNESS: 1.6±0.05mm



HOW TO MATE AND UNMATE

MATE: ①——→④

UNMATE: ⑤——→⑦

SMP TECHNOLOGY, INC.

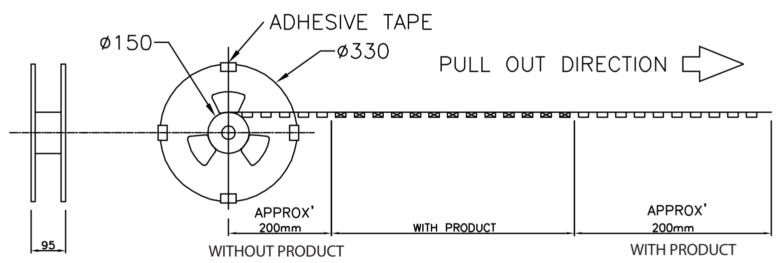
DDR SO DIMM Socket, 204 Position, 1.5 Volt

Standard Orientation, Right Angle, 5.2mm Height; Type 2

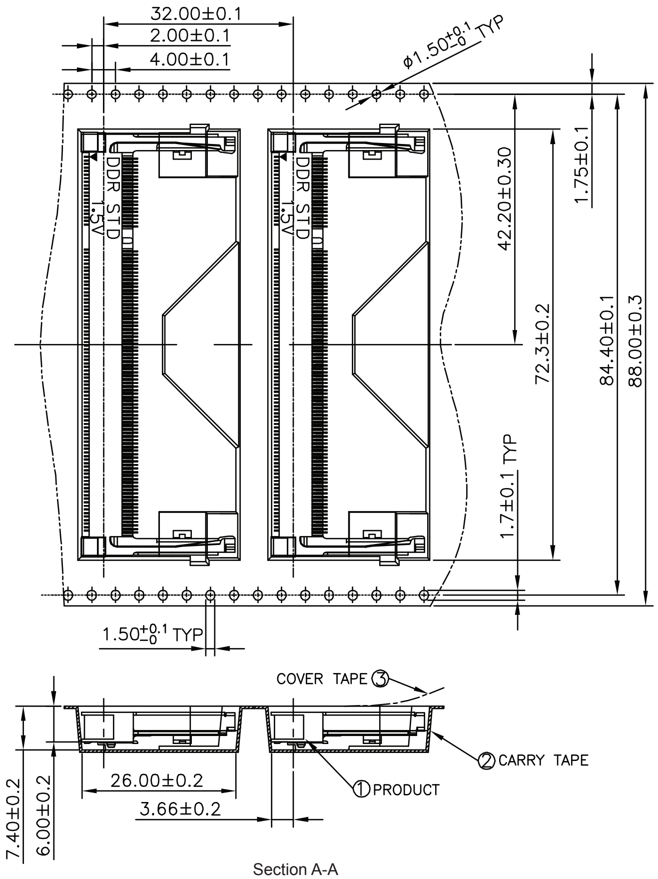
P/N: B030-2043-A0XX-Z

Pg: 3 of 5

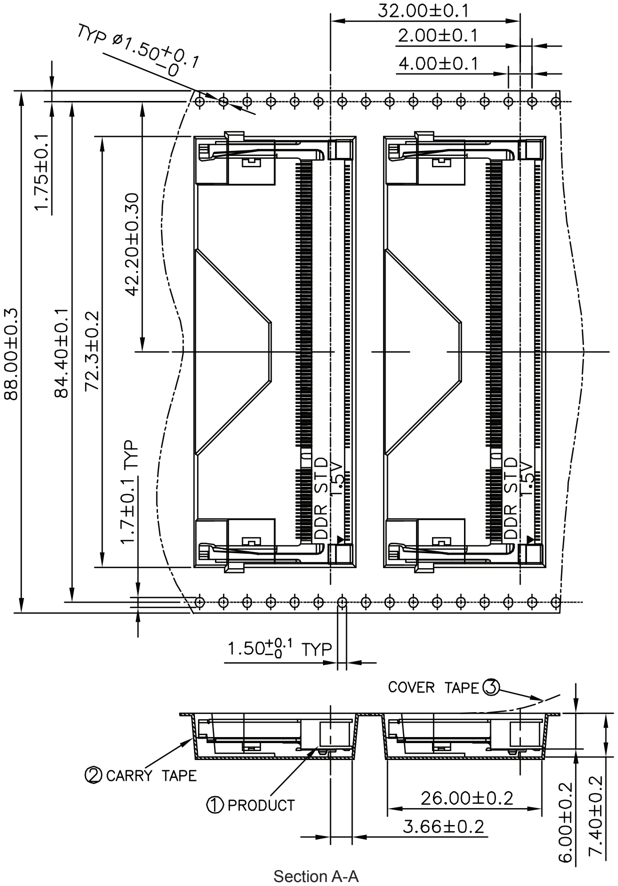
TOL. DEC. .X +/- 0.40 .XX +/- 0.25 .XXX +/- 0.15 .XXXX +/- 0.05 ANGLE +/- 3° UNIT: mm



NOTES:
1. PACKAGING MATERIAL IN PLASTIC, RUBBER, INK, PIGMENT AND MUST MEET CONTROLLED SUBSTANCES SPEC PER WI-PB-22.
  * CADMIUM AND CADMIUM COMPOUNDS NOT TO EXCEED : 5 PPM.
  * LEAD, CADMIUM, CHROM VI AND MERCURY NOT TO EXCEED : 100 PPM (COMBINED)
2. CARRIER TAPES, COVER TAPES, REELS AND TAPED COMPONETS MUST MEET THE REQUIREMENTS DEFINED PER EIA-481-B.
3. DIMENSION :
  3.1 REEL: H =95, øA=330
  3.2 SHIPPING CARTON : L = 335, W =335, H = 248
4. QUANTITY :
  4.1 PRIMARY PACKAGING : 200PCS / REEL
  4.2 SECONDARY PACKAGING : 2 REELS / CARTON (400PCS)
5. WEIGHT :
  5.1 NET WEIGHT : 1.49Kg / REEL, 2.98 Kg / CARTON.
  5.2 GROOS WEIGHT : 1.94 Kg / REEL, 3.87 Kg / CARTON
6. PEELING RESISTANCE : 0.1~0.7N (10.2gf ~ 71.4gf)
7. PEELING SPEED : 300mm / MINUTE.



Section A-A
Packaging Direction: Tape & Reel Normal



Section A-A
Packaging Direction: Tape & Reel Reverse

SMP TECHNOLOGY, INC.

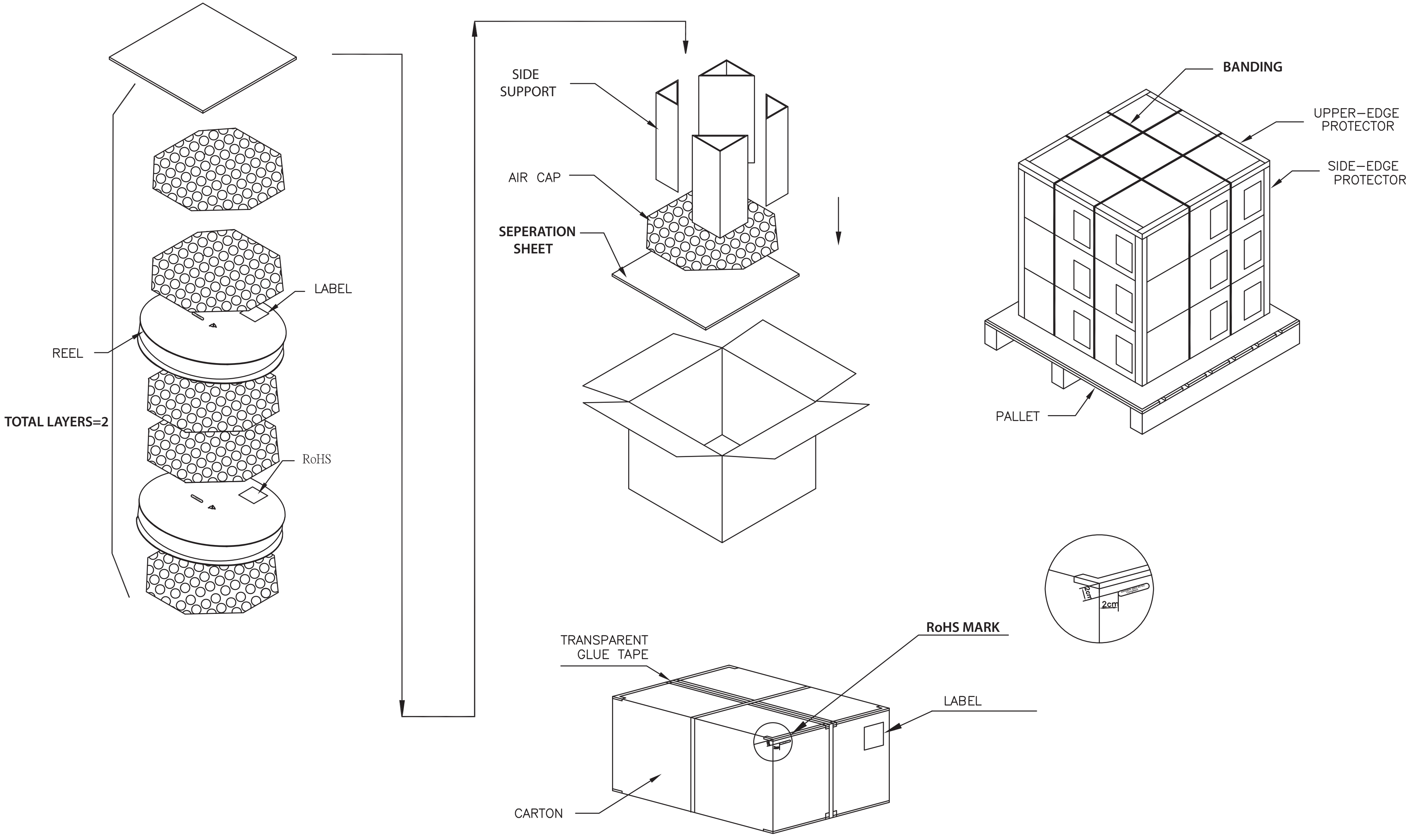
DDR SO DIMM Socket, 204 Position, 1.5 Volt

Standard Orientation, Right Angle, 5.2mm Height; Type 2

P/N: B030-2043-A0XX-Z

Pg: 4 of 5

TOL. DEC. .X +/- 0.40 .XX +/- 0.25 .XXX +/- 0.15 .XXXX +/- 0.05 ANGLE +/- 3° UNIT: mm



SMP TECHNOLOGY, INC.

DDR SO DIMM Socket, 204 Position, 1.5 Volt

Standard Orientation, Right Angle, 5.2mm Height; Type 2

P/N: B030-2043-A0XX-Z

Pg: 5 of 5

TOL. DEC. .X +/- 0.40 .XX +/- 0.25 .XXX +/- 0.15 .XXXX +/- 0.05 ANGLE +/- 3° UNIT: mm